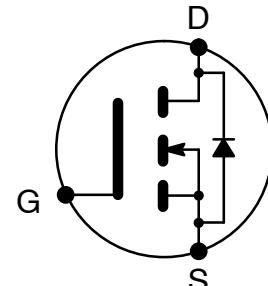




NTE2915
MOSFET
N-Channel, Enhancement Mode
High Speed Switch
TO220 Type Package

Features:

- Low Gate-to-Drain Charge to Reduce Switching Losses
- Fully Characterized Capacitance Including Effective C_{oss} to Simplify Design
- Fully Characterized Avalanche Voltage and Current



Applications:

- High Frequency DC-DC Converters

Absolute Maximum Ratings:

Continuous Drain Current ($V_{GS} = 10V$), I_D	
$T_C = +25^\circ C$	31A
$T_C = +100^\circ C$	21A
Pulsed Drain Current (Note 1), I_{DM}	124A
Power Dissipation ($T_C = +25^\circ C$), P_D	200W
Linear Derating Factor	1.3W/ $^\circ C$
Gate-Source Voltage, V_{GS}	$\pm 30V$
Peak Diode Recovery dv/dt (Note 2), dv/dt	5.9V/ns
Single Pulse Avalanche Energy (Note 3), E_{AS}	420mJ
Avalanche Current (Note 1), I_{AR}	18A
Repetitive Avalanche Energy (Note 1), E_{AR}	20mJ
Operating Junction Temperature Range, T_J	-55° to +175° $^\circ C$
Storage Temperature Range, T_{stg}	-55° to +175° $^\circ C$
Lead Temperature (During Soldering, 1.6mm from Case, 10 sec max.), T_L	+300° $^\circ C$
Maximum Thermal Resistance, Junction-to-Case, R_{thJC}	0.75° $^\circ C/W$
Typical Thermal Resistance, Case-to-Sink (Flat, Greased Surface), R_{thCS}	0.5° $^\circ C/W$
Maximum Thermal Resistance, Junction-to-Ambient, R_{thJA}	62° $^\circ C/W$

Note 1. Repetitive rating: pulse width limited by maximum channel temperature.

Note 2. $I_{SD} \leq 18A$, $di/dt \leq 110A/s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J +175^\circ C$.

Note 3. Starting $T_J = +25^\circ C$, $L = 3.8mH$, $R_G = 25\Omega$, $I_{AS} = 18A$.

Electrical Characteristics: ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	200	-	-	V
Breakdown Voltage Temperature Coefficient	$\pm V_{(\text{BR})\text{DSS}}/\pm T_J$	Reference to $+25^\circ\text{C}$, $I_D = 1\text{mA}$	-	0.25	-	$\text{V}/^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 18\text{A}$, Note 4	-	-	0.082	Ω
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	3.0	-	5.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 200\text{V}, V_{GS} = 0\text{V}$	-	-	25	μA
		$V_{DS} = 160\text{V}, V_{GS} = 0\text{V}, T_J = +150^\circ\text{C}$	-	-	250	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 30\text{V}$	-	-	± 100	nA
Dynamic Characteristics						
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{V}, I_D = 18\text{A}$	17	-	-	S
Total Gate Charge	Q_g	$I_D = 18\text{A}, V_{DS} = 160\text{V}, V_{GS} = 10\text{V}$, Note 4	-	70	110	nC
Gate-to-Source Charge	Q_{gs}		-	18	27	nC
Gate-to-Drain ("Miller") Charge	Q_{gd}		-	33	49	nC
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 100\text{V}, I_D = 18\text{A}, R_G = 2.5\Omega, R_D = 4.5\Omega$, Note 4	-	16	-	ns
Rise Time	t_r		-	38	-	ns
Turn-Off Delay Time	$t_{d(off)}$		-	26	-	ns
Fall Time	t_f		-	10	-	ns
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$	-	2370	-	pF
Output Capacitance	C_{oss}		-	390	-	pF
Reverse Transfer Capacitance	C_{rss}		-	78	-	pF
Output Capacitance	C_{oss}	$V_{GS} = 0\text{V}, V_{DS} = 1\text{V}, f = 1\text{MHz}$	-	2860	-	pF
		$V_{GS} = 0\text{V}, V_{DS} = 160\text{V}, f = 1\text{MHz}$	-	150	-	pF
Effective Output Capacitance	$C_{oss\ eff.}$	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V to } 160\text{V}$, Note 5	-	170	-	pF

Note 4. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Note 5. $C_{oss\ eff.}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Source-Drain Ratings and Characteristics:

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	I_S		-	-	31	A
Pulsed Source Current (Body Diode)	I_{SM}	Note 1	-	-	124	A
Diode Forward Voltage	V_{SD}	$I_S = 18\text{A}, V_{GS} = 0\text{V}, T_J = +25^\circ\text{C}$, Note 4	-	-	1.3	V
Reverse Recovery Time	t_{rr}	$T_J = +25^\circ\text{C}, I_F = 18\text{A}, di/dt = 100\text{A}/\mu\text{s}$, Note 4	-	200	300	ns
Reverse Recovery Charge	Q_{rr}		-	1.7	2.6	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$)				

Note 1. Repetitive rating: pulse width limited by maximum channel temperature.

Note 4. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

